

MATERIAL DECLARATION SHEET



Material Number	CDSOT236-0504C			
Product Line	Semiconductor Products			
Compliance Date	2020/12/7			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.5000	Silicon	7440-21-3	100.00%	3.125%	3.125%
2	Lead frame	Copper Alloy	3.3353	Copper	7440-50-8	95.29%	20.846%	21.876%
			0.0875	Iron	7439-89-6	2.50%	0.547%	
			0.0035	phosphorous	7723-14-0	0.10%	0.022%	
			0.0035	Zinc	7440-66-6	0.10%	0.022%	
			0.0700	Silver	7440-22-4	2.00%	0.438%	
			0.0002	Lead	7439-92-1	0.01%	0.001%	
3	Epoxy	Polymer	0.48	Si-oxide Quartz	14808-60-7	59.46%	3.717	6.251%
			0.32	Epoxy resin	9003-36-5	39.19%	2.449	
			0.01	Epoxy resin	25068-38-6	1.35%	0.085	
4	Wire	Noble metal	0.9999	Gold	7440-57-5	99.99%	6.2494%	6.25%
			0.0001	Misc, not to declare	/	0.01%	0.0006%	
5	Mold Compound	Polymer	0.4500	Epoxy Resin	Trade secret	5.00%	2.812%	56.248%
			0.1800	Phenol Resin	Trade secret	2.00%	1.126%	
			0.0810	Carbon Black	1333-86-4	0.90%	0.507%	

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			7.8399	Amorphous silica	60676-86-0	87.11%	48.997%	
			0.4490	Crystal silica	14808-60-7	4.99%	2.806%	
6	Plating	Plating	0.9999	Tin	7440-31-5	99.99%	6.249%	6.25%
			0.0001	Misc., not to declare	/	0.01%	0.001%	
		Total weight	16 mg					

This Document was updated on: 3/31/2022

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.